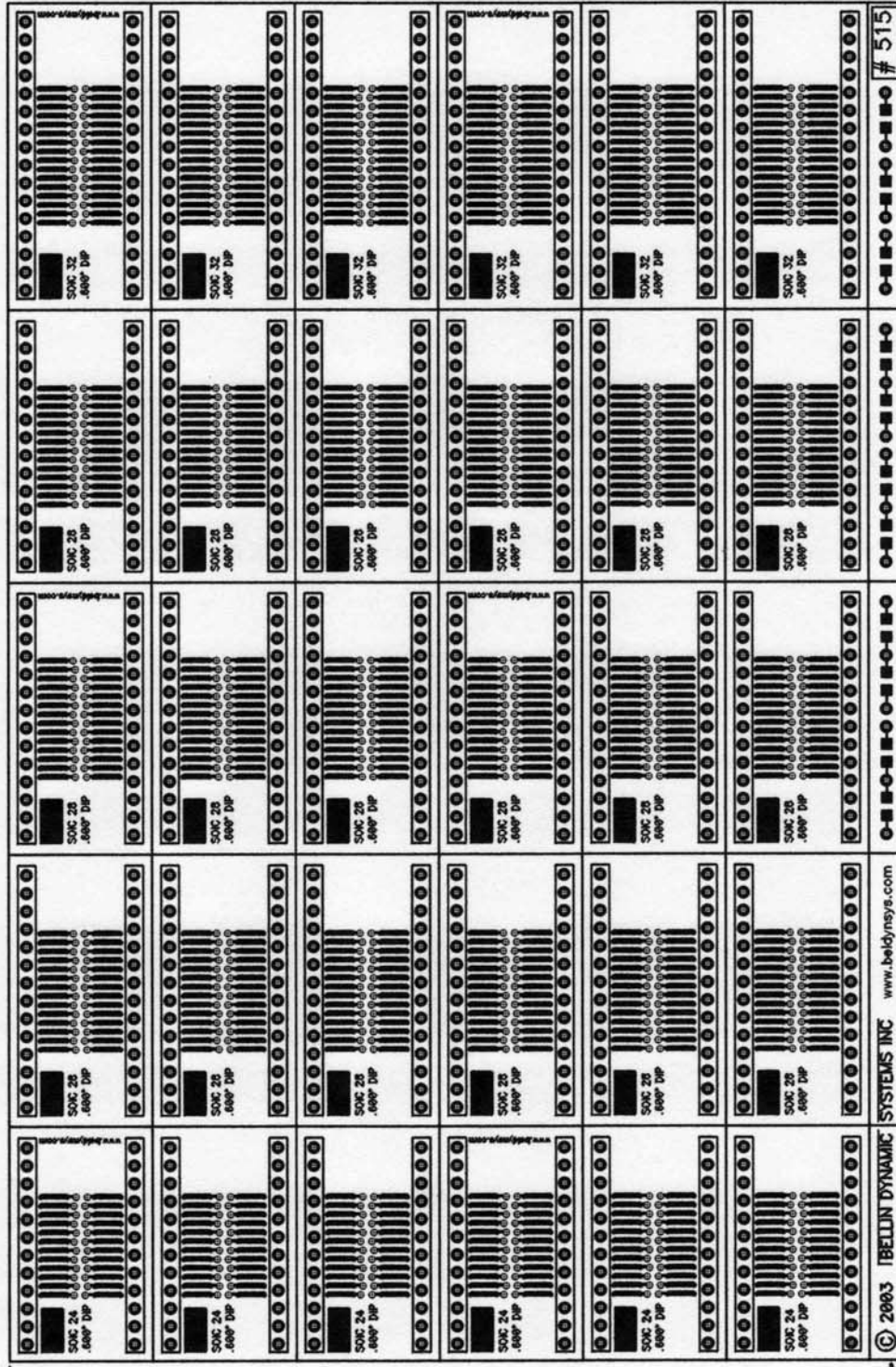


front side board thickness 0.031" all 0.070" pads have 0.050" plated through holes on 0.100" grid  
 print 1:1 to fit check components lines between adapters grooved for easy snap-apart by hand

5.000"



0.000"

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# 515

7.600"

Bellin Dynamic Systems Inc 211 South State College #319, Anaheim California 92806	
Tolerances: .XX = +/- .03" .XXX = +/- .010"	Title Board, SOIC TO DIP .600"
Drawn: P Bellin	Part #: 515
Check: P Bellin	Doc #: 20165.PCB
Part Rev: None Sheet 1 Of 1	